

PCB PATTERN LAYOUT  
GENERAL TOLERANCE ±0.05

- NOTES:
- MATERIAL:
    - HOUSING: HALOGEN FREE PLASTIC, HIGH TEMP., UL94V-0;
    - CONTACT: COPPER ALLOY
    - FITTING NAIL: COPPER ALLOY
  - FINISH:
    - CONTACT:
      - 50~100u" NICKEL UNDERPLATING OVERALL
      - 1:GOLD FLASH PLATING(1~3u")
      - N: 100~200u" MATT TIN PLATING
      - L: 100~200u" PURE TIN PLATING
      - P:GOLD FLASH(1~3U") ON CONTACT AND 80~150U" MATT TIN ON SOLDER
      - C:15u" GOLD ON CONTACT AND 80~150U" MATT TIN ON SOLDER
    - FITTING NAIL:
      - 50~100u" NICKEL UNDERPLATING OVERALL
      - 1:GOLD FLASH PLATING(1~3u")
      - N: 100~200u" MATT TIN PLATING
      - L: 100~200u" PURE TIN PLATING
  - REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
  - SPEC. PLS. REFER TO PS-50305-XXXX-XXX
  - PACKAGE PLS. REFER TO 88289-XXXX-TRP
  - PART NUMBER

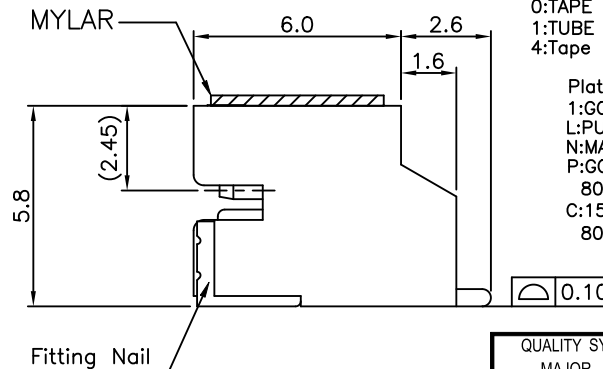
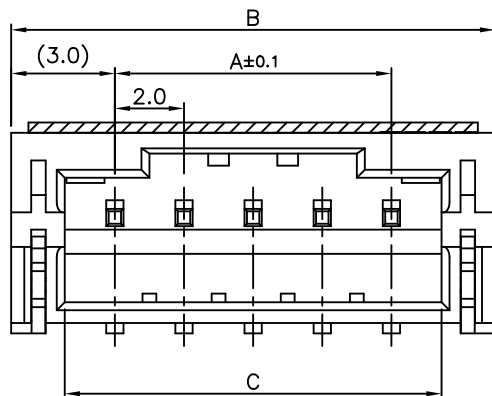
P/N LEGEND  
50308-XXX X X-XXX

XXX	Housing color	PACKING
001	BLACK	88289-XXXX-TRP
002	NATURAL	88289-XXXX-TRP

- CKTS
- Packing
- 0:TAPE & REEL
  - 1:TUBE
  - 4:Tape & Reel with Mylar

- Plating
- 1:GOLD FLASH
  - L:PURE TIN LEAD FREE
  - N:MATT TIN LEAD FREE
  - P:GOLD FLASH(1~3U") ON CONTACT AND 80~150U" MATT TIN ON SOLDER
  - C:15u" GOLD ON CONTACT AND 80~150U" MATT TIN ON SOLDER

CKT	Dim A	Dim B	Dim C	MYLAR
2	2.0	8.0	4.9	WTT12-50308
3	4.0	10.0	6.9	
4	6.0	12.0	8.9	
5	8.0	14.0	10.9	
6	10.0	16.0	12.9	
7	12.0	18.0	14.9	
8	14.0	20.0	16.9	
9	16.0	22.0	18.9	
10	18.0	24.0	20.9	
11	20.0	26.0	22.9	
12	22.0	28.0	24.9	
13	24.0	30.0	26.9	
14	26.0	32.0	28.9	
15	28.0	34.0	30.9	
16	30.0	36.0	32.9	
17	32.0	38.0	34.9	
18	34.0	40.0	36.9	
19	36.0	42.0	38.9	
20	38.0	44.0	40.9	



QUALITY SYMBOLS MAJOR Ⓢ CRITICAL Ⓢ	DRAWN BY Xu,Zhonglin	DATE 20/10/30	
GENERAL TOLERANCES (UNLESS SPECIFIED)	CHECKED BY Lu, Jing Quan	DATE 20/10/30	
X. ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°	APPROVED BY hsieh, fu yu	DATE 20/10/30	
	UNITS mm	SIZE A4	DWG NO. N/A
	SCALE 5 : 1	SHEET NO. 1 OF 1	REV G
			PART NO. 50308-XXXX-XXX